

# INTERCONNECTS

## SERIES 834 & 835 • .100" GRID OFP® PASS-THROUGH SOCKETS Ø.030" & □.025" PINS • SINGLE AND DOUBLE ROW STRIPS

- 834/835 Series Pass-Through Sockets have a low .130" profile and will accept Ø.030" round pin, as well as industry standard .025" square pin headers.
- They are typically used to interconnect two or more parallel circuit boards.
- Sockets are designed for hand, wave or reflow\* soldering. The high temperature insulator is compatible with all solder processes.
- Unique ORGANIC FIBRE PLUG® barriers prevent solder, paste or flux from contaminating the internal spring contacts. After soldering, the OFP® barriers are pushed out of the socket when the mating header is inserted.
- Mill-Max sockets use a receptacle consisting of a precision-machined brass sleeve with a press-fit beryllium copper "multi-finger" spring contact.
- Recommended mounting holes are Ø.046 ±.003" PTH (1,2 mm drilled prior to plating).

\*Intrusive reflow (also called "pin-in-paste") is a technique of using conventional through-hole components in a reflow soldering process. The pass-through socket is placed into plated through-holes in the circuit board (solder paste has previously been screen printed on pads adjacent to the holes) and the board is reflowed in the same pass as other SMT components. Solder will fill the plated through-holes and achieve solder joints as reliable as wave soldering. The OFP® barrier prevents solder paste from being picked up inside the contact during assembly.

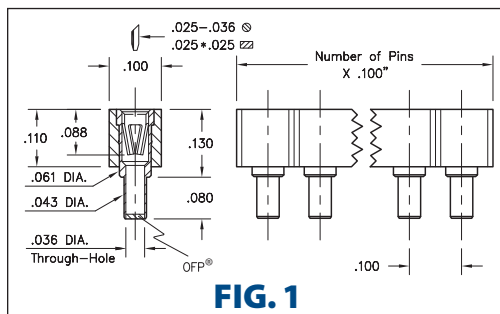
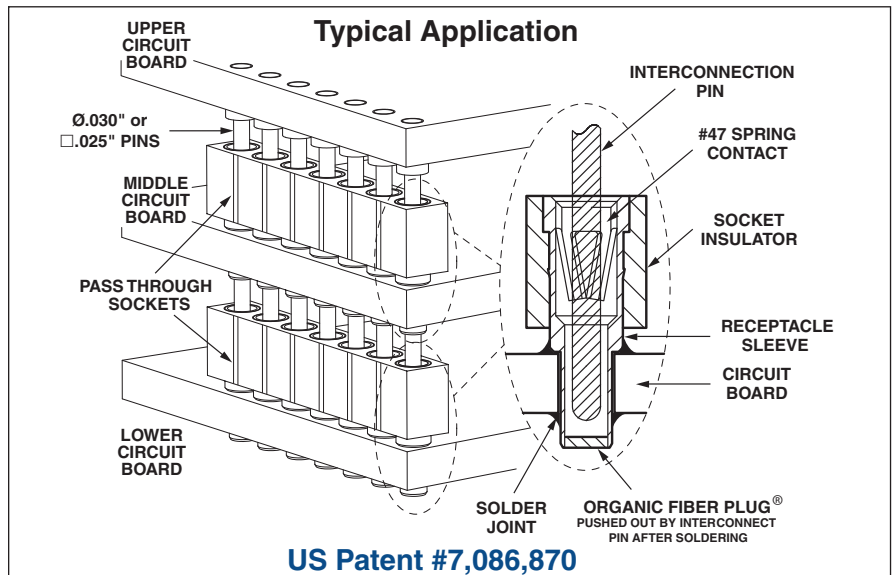
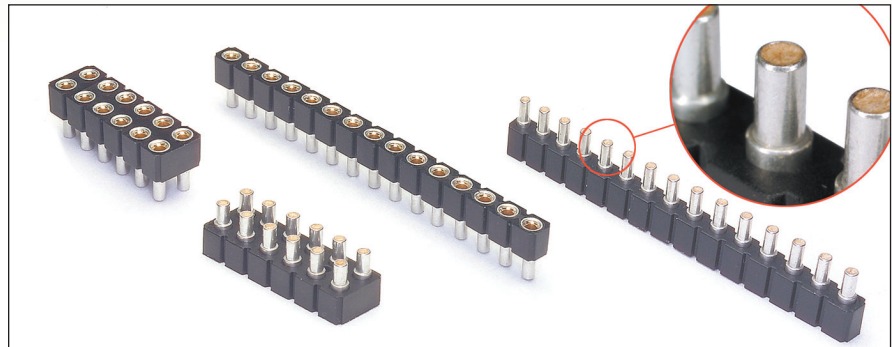


FIG. 1

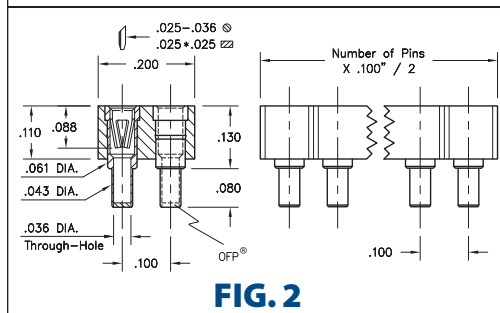


FIG. 2

## ORDERING INFORMATION

FIG. 1	Series 834...001 Single Row OFP® Pass-Through Socket	
	834-XX-0	-10-001000
	Specify number of pins	01-64
FIG. 2	Series 835...001 Double Row OFP® Pass-Through Socket	
	835-XX-0	-10-001000
	Specify number of pins	04-72
<div> <div>RoHS-2 2011/65/EU</div> <div>XX=Plating Code See Below</div> <div>For Electrical, Mechanical &amp; Environmental Data, See page 264</div> </div>		
SPECIFY PLATING CODE XX=		
Sleeve (Pin)	200 µ"Sn/Pb	200 µ"Sn
Contact (Clip)	30 µ" Au	30 µ" Au
		Au Flash

